DA4J104K

Silicon epitaxial planar type

For high speed switching circuits

■ Features

- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Basic Part Number

Double DA2J104 (Parallel)

■ Packaging

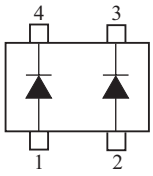
Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Package

- Code
  SMini4-F3-B
- Pin Name
  1: Anode-1 3: Cathode-2
  2: Anode-2 4: Cathode-1

■ Marking Symbol: C1

■ Internal Connection



■ Absolute Maximum Ratings $T_a = 25°C$

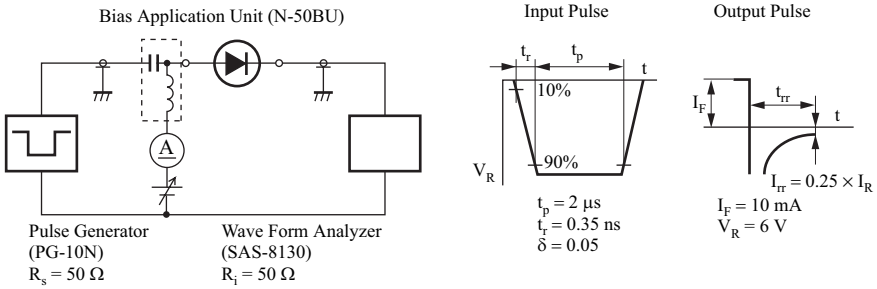
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	80	V
Maximum peak reverse voltage	V_{RM}	80	V
Forward current *1	I_F	200	mA
Peak forward current	I_{FM}	600	mA
Non-repetitive peak forward surge current *2	I_{FSM}	1	A
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

Note) ∗1: I_F = 200 mA achieved with a printed circuit board.
∗2: 1 t = 1 s

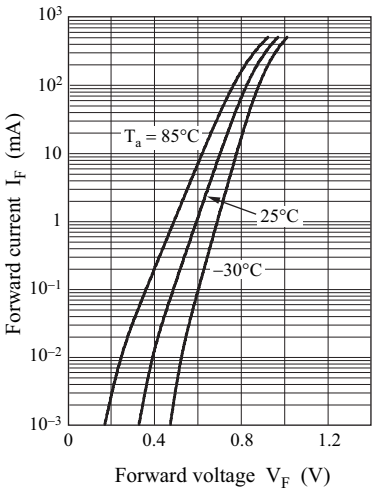
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 200 mA		0.90	1.10	V
Reverse voltage	V_R	I_R = 100 μA	80			V
Reverse current	I_{R1}	V_R = 15 V			50	nA
	I_{R2}	V_R = 75 V			500	
Terminal capacitance	C_t	V_R = 0 V, f = 1 MHz			4	pF
Reverse recovery time *	t_{rr}	I_F = 10 mA, V_R = 6 V, I_{rr} = 0.25 × I_R			10	ns

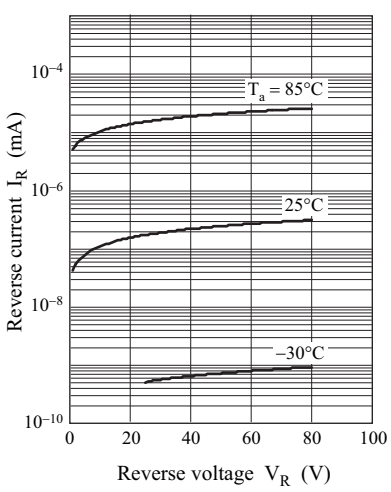
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 100 MHz
3. ∗: t_{rr} measurement circuit



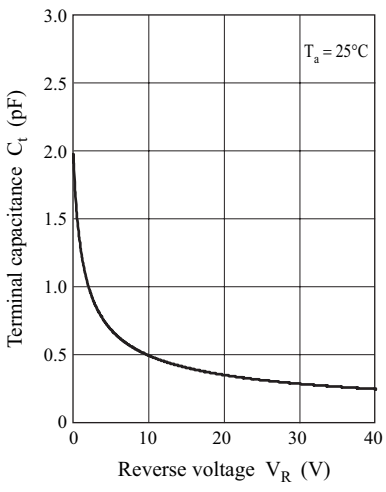
I_F — V_F



I_R — V_R

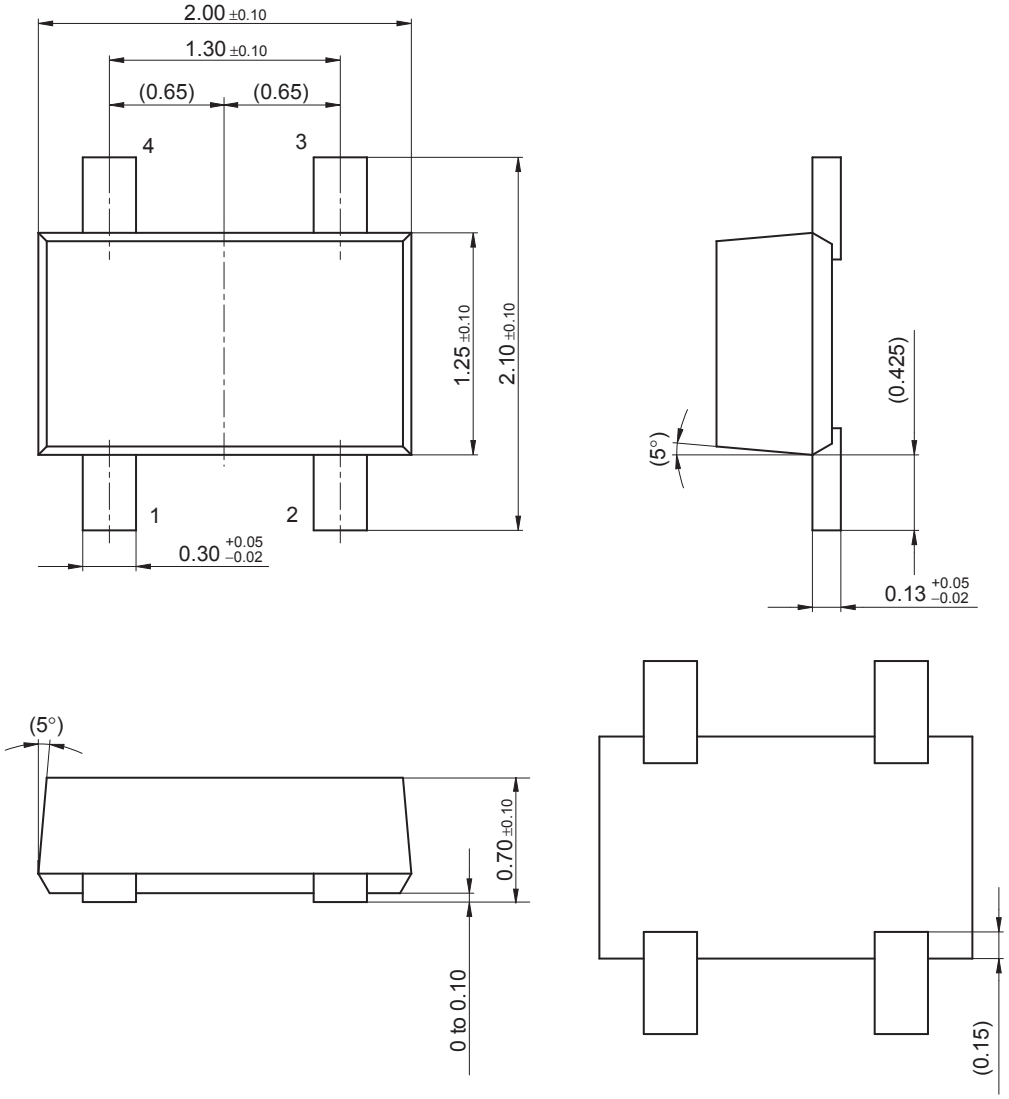


C_t — V_R



SMini4-F3-B

Unit: mm



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